

**INVENTORSHIP DECLARATION BY SOLE INVENTOR**

I, James L. Voelz, HEREBY DECLARE THAT:

My residence, mailing address, and citizenship are stated below next to my name.

I believe I am the original, first, and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

**METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC DEVICES AND  
MICROELECTRONIC DEVICES FORMED BY SUCH METHODS**

the specification of which:

- ☒ is attached hereto.
- ☐ was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with 37 C.F.R. §1.56, including, for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim priority benefits under 35 U.S.C. §119(a)-(d) or (f), §172, or §365(a)-(b) of any foreign or international application(s) for patent or inventor's certificate listed below in Table 1 and have also identified in Table 1 any such foreign or international application having a filing date before that of the application of which priority is claimed.

I hereby declare that all statements made herein of my knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. I understand that the execution of this document does not in itself establish an attorney-client relationship between the undersigned and Perkins Coie, LLP, or any of its attorneys.

Full name of Sole inventor: James L. Voelz

Citizenship: USA Mailing Address: 1943 NW 11th Avenue  
Meridian, Idaho 83642

Residence (if different): \_\_\_\_\_

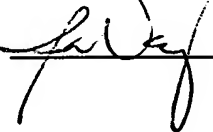
Inventor's Signature:  Date: 10/9/03

Table 1

<u>Country</u>	<u>App. No.</u>	<u>Filing Date</u>	<u>Priority Not Claimed</u>
			<input type="checkbox"/>
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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: JAMES L. VOELZ  
FILED: CONCURRENTLY HEREWITH  
FOR: **METHODS FOR WAFER-LEVEL  
PACKAGING OF MICROELECTRONIC  
DEVICES AND MICROELECTRONIC  
DEVICES FORMED BY SUCH METHODS**

**Power of Attorney by Assignee and Certification**  
**Under 37 C.F.R. § 3.73(b)**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

I, the undersigned, acting on behalf of the Assignee of the entire right, title and interest in the above-identified patent application, by virtue of an Assignment filed concurrently herewith, appoint the attorneys and agents listed below to prosecute this application and transact all business with the U.S. Patent and Trademark Office in connection therewith. This appointment is to the exclusion of the inventor(s) and their attorney(s) and agent(s) in accordance with the provisions of 37 C.F.R. § 3.71.

All prior powers of attorney for this application are hereby revoked. The Assignee hereby appoints

STEPHEN E. ARNETT, Registration No. 47,392  
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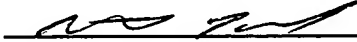
Direct all telephone calls to Paul T. Parker at (206) 359-3258. Address all correspondence to:

Customer No. 25096  
Perkins Coie LLP  
P.O. Box 1247  
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In accordance with 37 C.F.R. § 3.73(b), I hereby certify that I am empowered to act on behalf of the Assignee. To the best of my knowledge and belief, title is in the Assignee, as evidenced by the Assignment noted above.

I further declare that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18, USC § 1001 and that such willful false statements may jeopardize the validity of this application or any patent resulting therefrom.

ASSIGNEE: MICRON TECHNOLOGY, INC.

Signature: 

Typed Name: Michael L. Lynch

Title: Chief Patent Counsel

Date: 10-13-2007

Address: 8000 South Federal Way

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